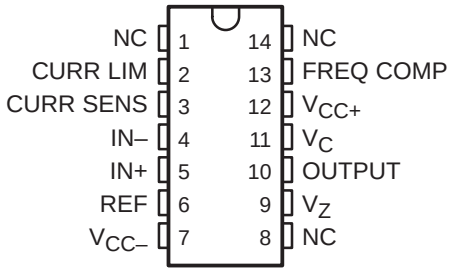
SLVS057D – AUGUST 1972 – REVISED JULY 1999

- **150-mA Load Current Without External Power Transistor**
- **Adjustable Current-Limiting Capability**
- **Input Voltages up to 40 V**
- **Output Adjustable From 2 V to 37 V**
- **Direct Replacement for Fairchild μA723C**

D OR N PACKAGE
(TOP VIEW)



description

The μA723 is a precision integrated-circuit voltage regulator, featuring high ripple rejection, excellent input and load regulation, excellent temperature stability, and low standby current. The circuit consists of a temperature-compensated reference-voltage amplifier, an error amplifier, a 150-mA output transistor, and an adjustable-output current limiter.

The μA723 is designed for use in positive or negative power supplies as a series, shunt, switching, or floating regulator. For output currents exceeding 150 mA, additional pass elements can be connected as shown in Figures 4 and 5.

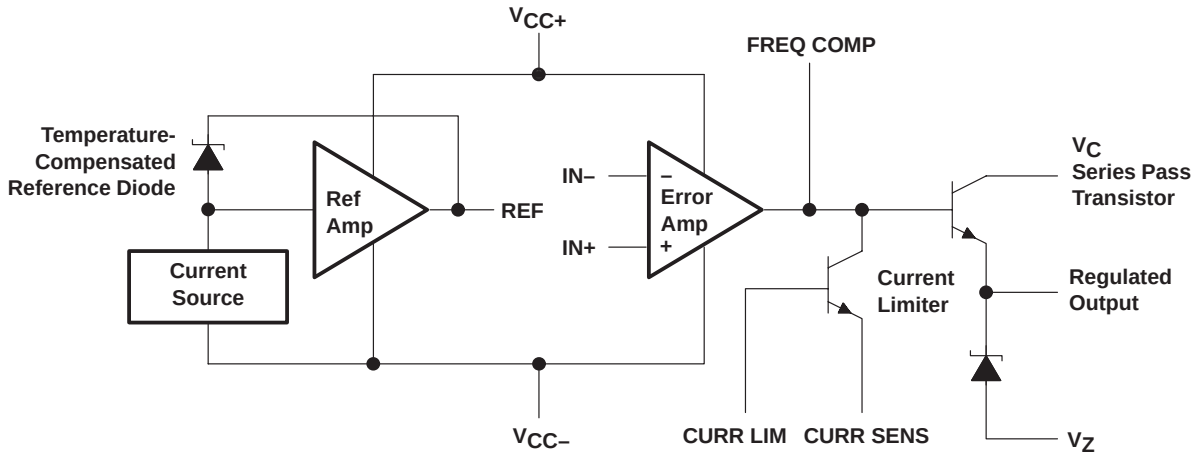
The μA723C is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

T_A	PACKAGED DEVICES		CHIP FORM (Y)
	PLASTIC DIP (N)	SMALL OUTLINE (D)	
0°C to 70°C	μA723CN	μA723CD	μA723Y

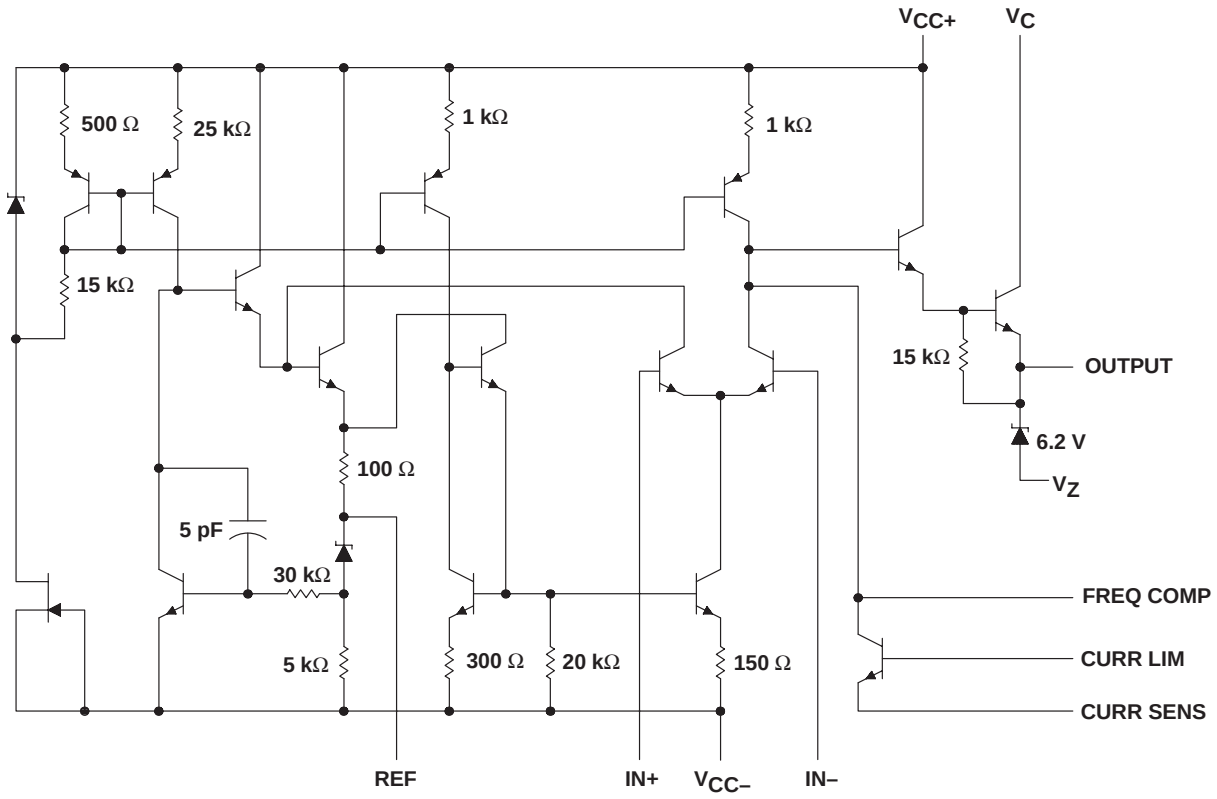
The D package is available taped and reeled. Add the suffix R to the device type (e.g., μA723CDR). Chip forms are tested at 25°C.

functional block diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

schematic



Resistor and capacitor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Peak voltage from V_{CC+} to V_{CC-} ($t_w \leq 50$ ms)	50 V
Continuous voltage from V_{CC+} to V_{CC-}	40 V
Input-to-output voltage differential	40 V
Differential input voltage to error amplifier	±5 V
Voltage between noninverting input and V_{CC-}	8 V
Current from V_Z	25 mA
Current from REF	15 mA
Package thermal impedance, θ_{JA} (see Notes 1 and 2): D package	86°C/W
N package	101°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or N package	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
Input voltage, V_I		9.5	40	V
Output voltage, V_O		2	37	V
Input-to-output voltage differential, $V_C - V_O$		3	38	V
Output current, I_O			150	mA
Operating free-air temperature range, T_A	μA723C	0	70	°C

electrical characteristics at specified free-air temperature (see Notes 3 and 4)

PARAMETER	TEST CONDITIONS		T_A	μA723C			UNIT
				MIN	TYP	MAX	
Input regulation	V_I = 12 V to V_I = 15 V		25°C		0.1	1	mV/V
	V_I = 12 V to V_I = 40 V		25°C		1	5	
	V_I = 12 V to V_I = 15 V		0°C to 70°C			3	
Ripple rejection	f = 50 Hz to 10 kHz,	C_{ref} = 0	25°C		74		dB
	f = 50 Hz to 10 kHz,	C_{ref} = 5 μF	25°C		86		
Output regulation			25°C		–0.3	–2	mV/V
			0°C to 70°C			–6	
Reference voltage, V_{ref}			25°C	6.8	7.15	7.5	V
Standby current	V_I = 30 V,	I_O = 0	25°C		2.3	4	mA
Temperature coefficient of output voltage			0°C to 70°C		0.003	0.015	%/°C
Short-circuit output current	R_{SC} = 10 Ω,	V_O = 0	25°C		65		mA
Output noise voltage	BW = 100 Hz to 10 kHz,	C_{ref} = 0	25°C		20		μV
	BW = 100 Hz to 10 kHz,	C_{ref} = 5 μF	25°C		2.5		

NOTES: 3. For all values in this table, the device is connected as shown in Figure 1 with the divider resistance as seen by the error amplifier ≤ 10 kΩ. Unless otherwise specified, $V_I = V_{CC+} = V_C$ = 12 V, V_{CC-} = 0, V_O = 5 V, I_O = 1 mA, R_{SC} = 0, and C_{ref} = 0.
4. Pulse-testing techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

electrical characteristics, T_A = 25°C (see Notes 3 and 4)

PARAMETER	TEST CONDITIONS		μA723Y			UNIT
			MIN	TYP	MAX	
Input regulation	V_I = 12 V to V_I = 15 V			0.1		mV/V
	V_I = 12 V to V_I = 40 V			1		
Ripple rejection	f = 50 Hz to 10 kHz,	C_{ref} = 0		74		dB
	f = 50 Hz to 10 kHz,	C_{ref} = 5 μF		86		
Output regulation				–0.3		mV/V
Reference voltage, V_{ref}				7.15		V
Standby current	V_I = 30 V,	I_O = 0		2.3		mA
Short-circuit output current	R_{SC} = 10 Ω,	V_O = 0		65		mA
Output noise voltage	BW = 100 Hz to 10 kHz,	C_{ref} = 0		20		μV
	BW = 100 Hz to 10 kHz,	C_{ref} = 5 μF		2.5		

NOTES: 3. For all values in this table, the device is connected as shown in Figure 1 with the divider resistance as seen by the error amplifier ≤ 10 kΩ. Unless otherwise specified, $V_I = V_{CC+} = V_C$ = 12 V, V_{CC-} = 0, V_O = 5 V, I_O = 1 mA, R_{SC} = 0, and C_{ref} = 0.
4. Pulse-testing techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

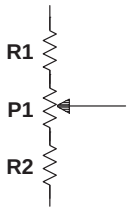
APPLICATION INFORMATION

Table 1. Resistor Values (kΩ) for Standard Output Voltages

OUTPUT VOLTAGE (V)	APPLICABLE FIGURES (SEE NOTE 5)	FIXED OUTPUT ±5%		OUTPUT ADJUSTABLE ±10% (SEE NOTE 6)		
		R1 (kΩ)	R2 (kΩ)	R1 (kΩ)	P1 (kΩ)	P2 (kΩ)
3.0	1, 5, 6, 9, 11, 12 (4)	4.12	3.01	1.8	0.5	1.2
3.6	1, 5, 6, 9, 11, 12 (4)	3.57	3.65	1.5	0.5	1.5
5.0	1, 5, 6, 9, 11, 12 (4)	2.15	4.99	0.75	0.5	2.2
6.0	1, 5, 6, 9, 11, 12 (4)	1.15	6.04	0.5	0.5	2.7
9.0	2, 4, (5, 6, 9, 12)	1.87	7.15	0.75	1.0	2.7
12	2, 4, (5, 6, 9, 12)	4.87	7.15	2.0	1.0	3.0
15	2, 4, (5, 6, 9, 12)	7.87	7.15	3.3	1.0	3.0
28	2, 4, (5, 6, 9, 12)	21.0	7.15	5.6	1.0	2.0
45	7	3.57	48.7	2.2	10	39
75	7	3.57	78.7	2.2	10	68
100	7	3.57	105	2.2	10	91
250	7	3.57	255	2.2	10	240
–6 (see Note 7)	3, 10	3.57	2.43	1.2	0.5	0.75
–9	3, 10	3.48	5.36	1.2	0.5	2.0
–12	3, 10	3.57	8.45	1.2	0.5	3.3
–15	3, 10	3.57	11.5	1.2	0.5	4.3
–28	3, 10	3.57	24.3	1.2	0.5	10
–45	8	3.57	41.2	2.2	10	33
–100	8	3.57	95.3	2.2	10	91
–250	8	3.57	249	2.2	10	240

NOTES: 5. The R1/R2 divider can be across either V_O or $V_{(ref)}$. If the divider is across $V_{(ref)}$, use the figure numbers without parentheses. If the divider is across V_O, use the figure numbers in parentheses.

6. To make the voltage adjustable, the R1/R2 divider shown in the figures must be replaced by the divider shown below.



Adjustable Output Circuit

7. For Figures 3, 8, and 10, the device requires a minimum of 9 V between V_{CC+} and V_{CC-} when V_O is equal to or more positive than –9 V.

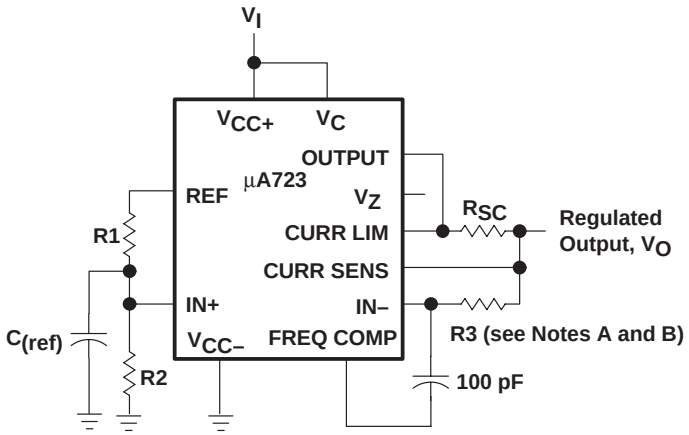
APPLICATION INFORMATION

Table 2. Formulas for Intermediate Output Voltages

OUTPUTS FROM 2 V TO 7 V SEE FIGURES 1, 5, 6, 9, 11, 12 (4) AND NOTE 5	OUTPUTS FROM 4 V TO 250 V SEE FIGURE 7 AND NOTE 5	CURRENT LIMITING
$V_O = V_{(ref)} \times \frac{R2}{R1 + R2}$	$V_O = \frac{V_{(ref)}}{2} \times \frac{R2 - R1}{R1}$ $R3 = R4$	$I_{(limit)} \approx \frac{0.65\ V}{R_{SC}}$
OUTPUTS FROM 7 V TO 37 V SEE FIGURES 2, 4, (5, 6, 9, 11, 12) AND NOTE 5	**OUTPUTS FROM –6 V TO –250 V SEE FIGURES 3, 8, 10 AND NOTES 5 AND 7**	**FOLDBACK CURRENT LIMITING SEE FIGURE 6**
$V_O = V_{(ref)} \times \frac{R1 + R2}{R2}$	$V_O = -\frac{V_{(ref)}}{2} \times \frac{R1 + R2}{R1}$ $R3 = R4$	$I_{(knee)} \approx \frac{V_O R3 + (R3 + R4)\ 0.65\ V}{R_{SC} R4}$ $I_{OS} \approx \frac{0.65\ V}{R_{SC}} \times \frac{R3 + R4}{R4}$

NOTES: 5. The R1/R2 divider can be across either V_O or $V_{(ref)}$. If the divider is across $V_{(ref)}$, use figure numbers without parentheses. If the divider is across V_O, use the figure numbers in parentheses.

7. For Figures 3, 8, and 10, the device requires a minimum of 9 V between V_{CC+} and V_{CC-} when V_O is equal to or more positive than –9 V.

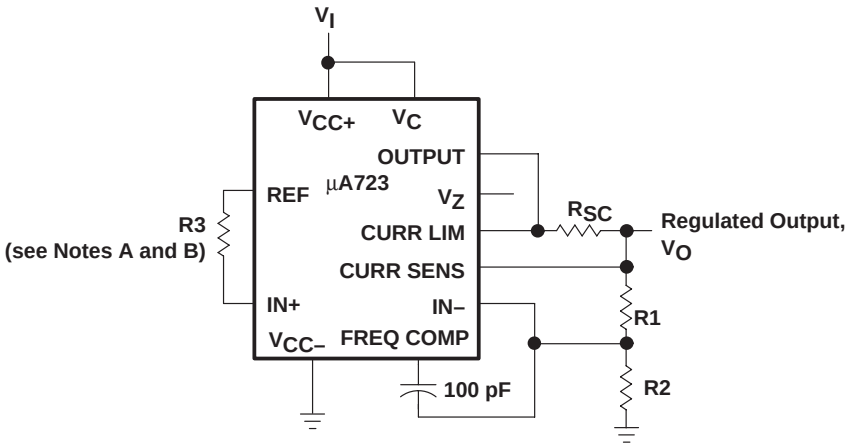


NOTES: A. $R3 = \frac{R1 \times R2}{R1 + R2}$ for a minimum α_{V_O}

B. R3 can be eliminated for minimum component count. Use direct connection (i.e., $R_3 = 0$).

Figure 1. Basic Low-Voltage Regulator (V_O = 2 V to 7 V)

APPLICATION INFORMATION



NOTES: A. $R3 = \frac{R1 \times R2}{R1 + R2}$ for a minimum α_{V_O}

B. R3 can be eliminated for minimum component count. Use direct connection (i.e., $R_3 = 0$).

Figure 2. Basic High-Voltage Regulator (V_O = 7 V to 37 V)

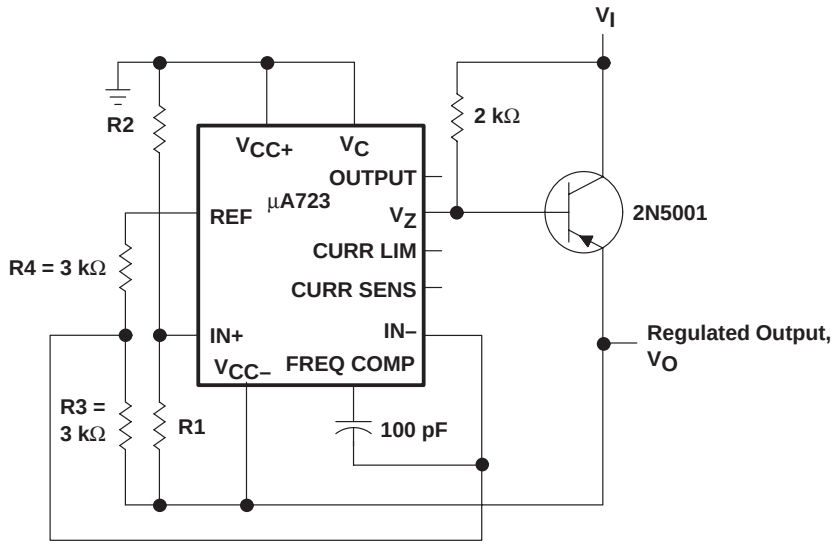


Figure 3. Negative-Voltage Regulator

APPLICATION INFORMATION

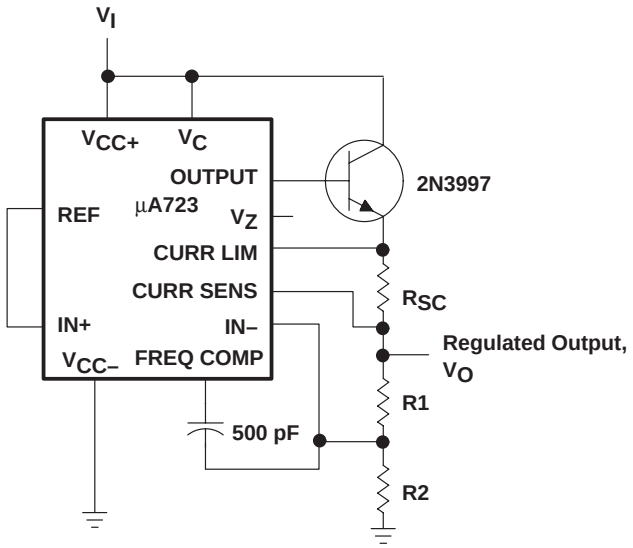


Figure 4. Positive-Voltage Regulator (External npn Pass Transistor)

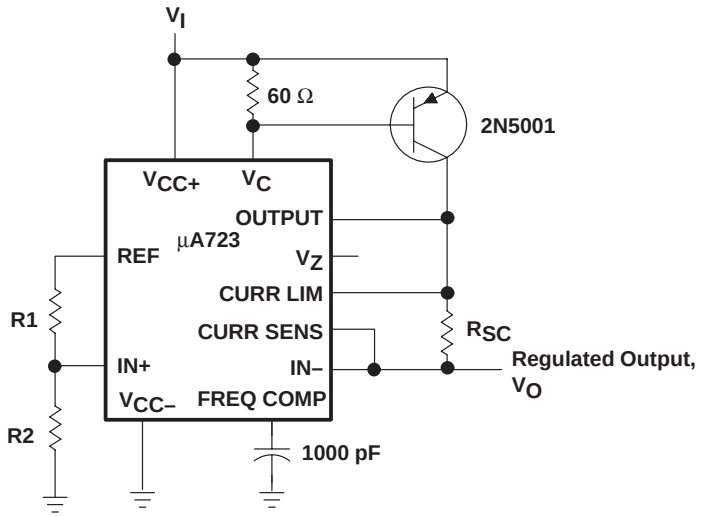


Figure 5. Positive-Voltage Regulator (External pnp Pass Transistor)

APPLICATION INFORMATION

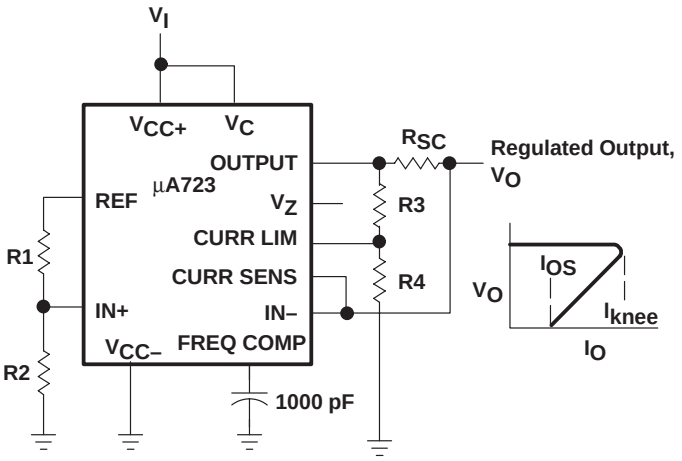


Figure 6. Foldback Current Limiting

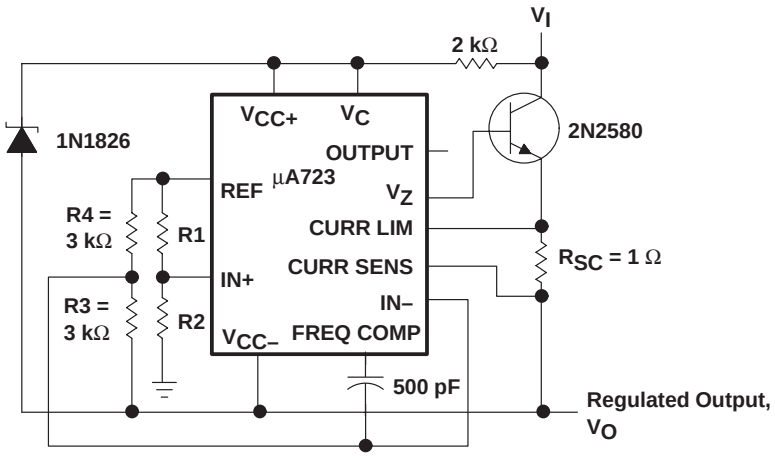


Figure 7. Positive Floating Regulator

APPLICATION INFORMATION

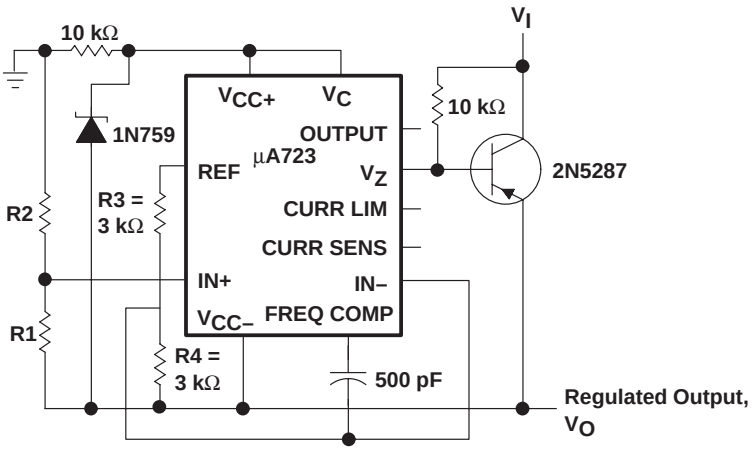
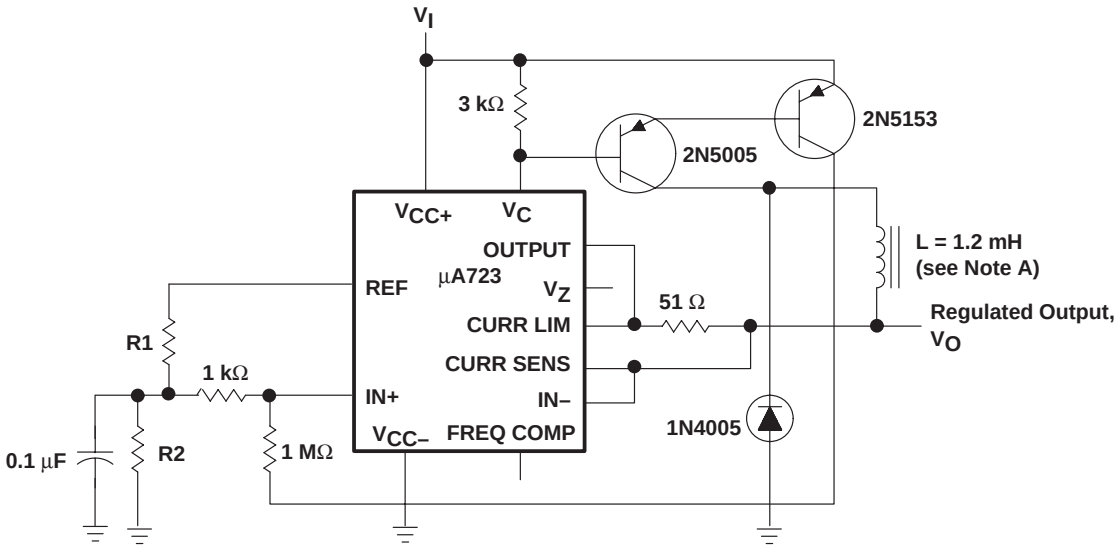


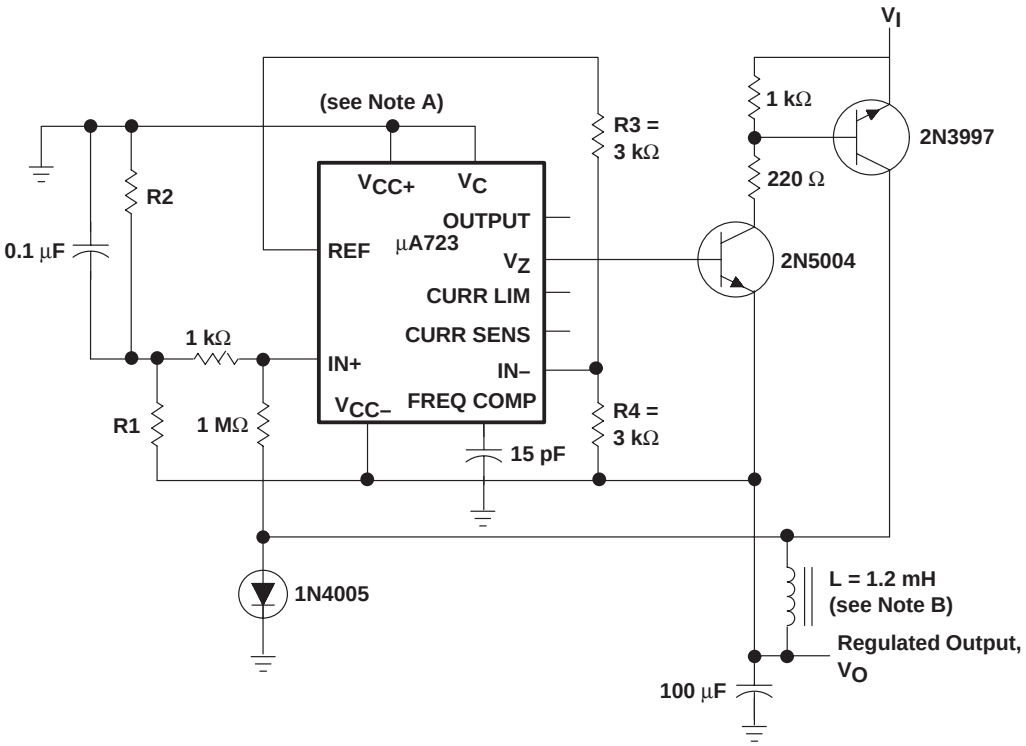
Figure 8. Negative Floating Regulator



NOTE A: L is 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 potted core, or equivalent, with a 0.009-inch air gap.

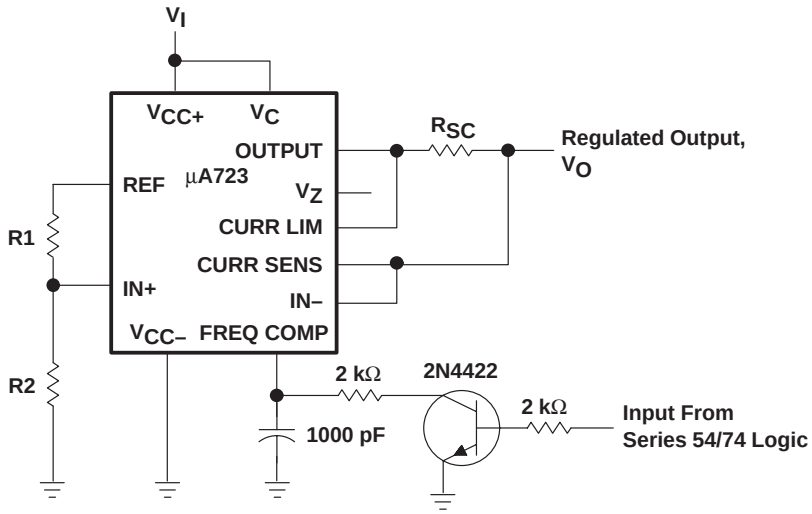
Figure 9. Positive Switching Regulator

APPLICATION INFORMATION



NOTES: A. The device requires a minimum of 9 V between V_{CC+} and V_{CC-} when V_O is equal to or more positive than –9 V.
B. L is 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 potted core, or equivalent, with a 0.009-inch air gap.

Figure 10. Negative Switching Regulator



NOTE A: A current-limiting transistor can be used for shutdown if current limiting is not required.

Figure 11. Remote Shutdown Regulator With Current Limiting

APPLICATION INFORMATION

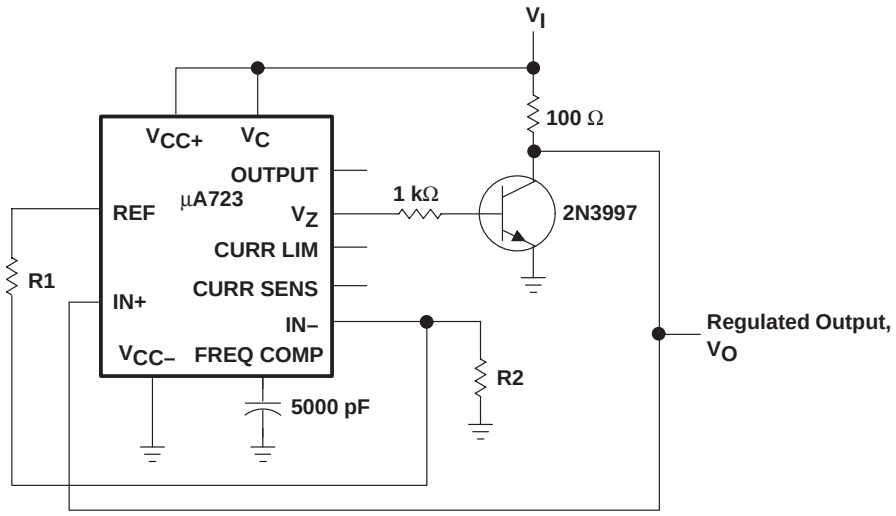


Figure 12. Shunt Regulator

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UA723CD	Active	Production	SOIC (D) | 14	50 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CDR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CN	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UA723CN
UA723CNSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

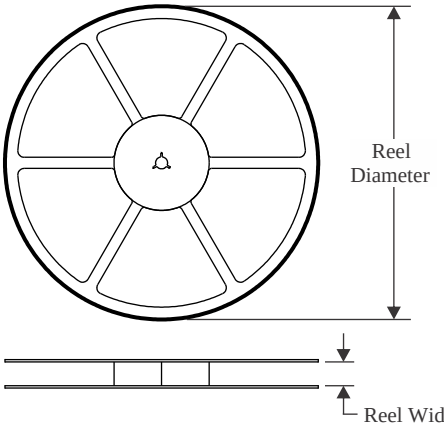
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

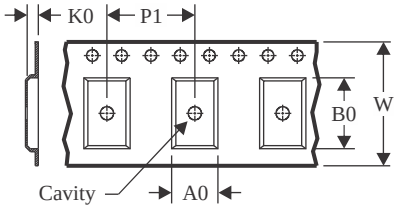
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

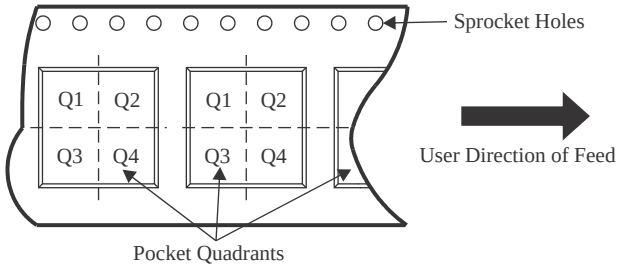


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

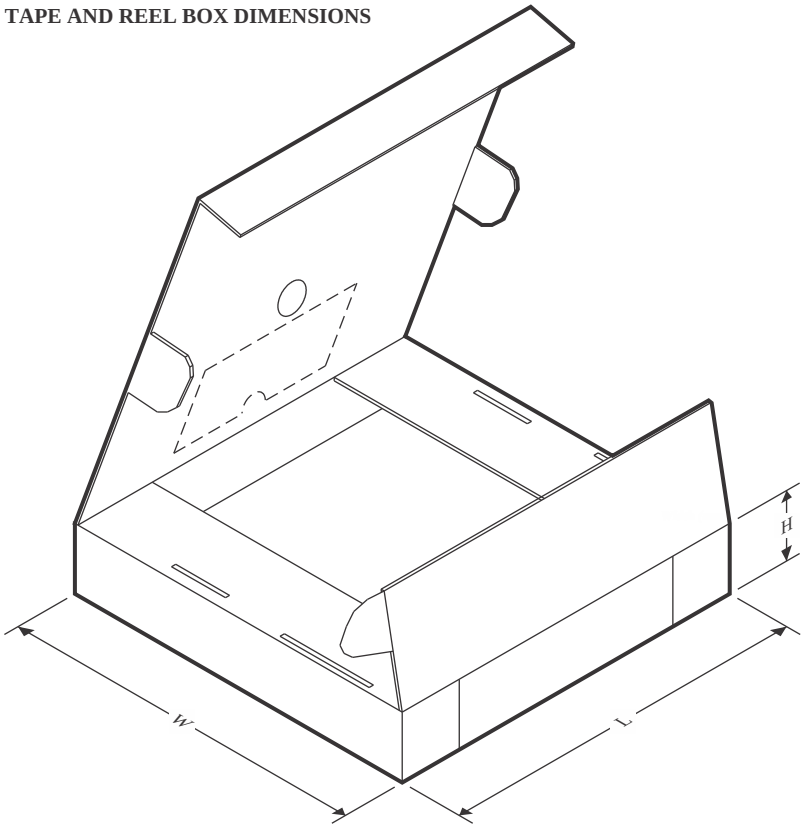
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA723CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
UA723CNSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

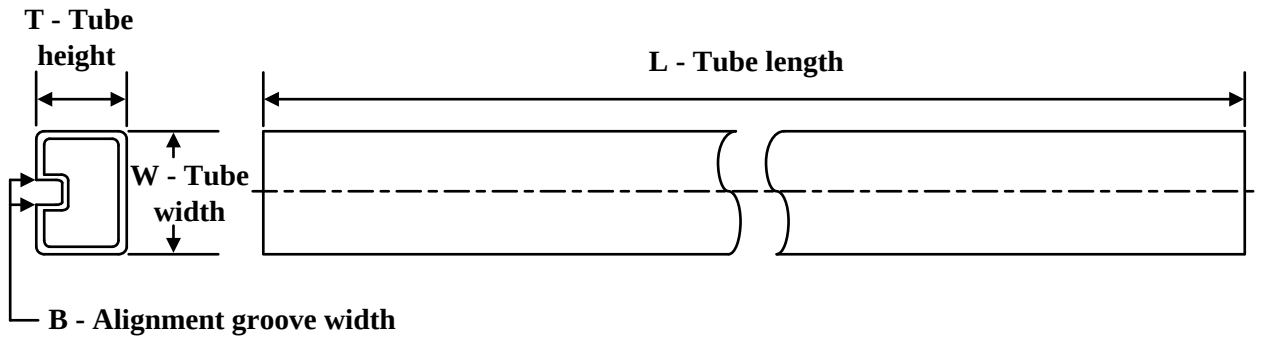
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

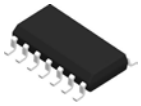
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA723CDR	SOIC	D	14	2500	356.0	356.0	35.0
UA723CNSR	SOP	NS	14	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
UA723CD	D	SOIC	14	50	506.6	8	3940	4.32
UA723CDE4	D	SOIC	14	50	506.6	8	3940	4.32
UA723CN	N	PDIP	14	25	506	13.97	11230	4.32
UA723CNE4	N	PDIP	14	25	506	13.97	11230	4.32

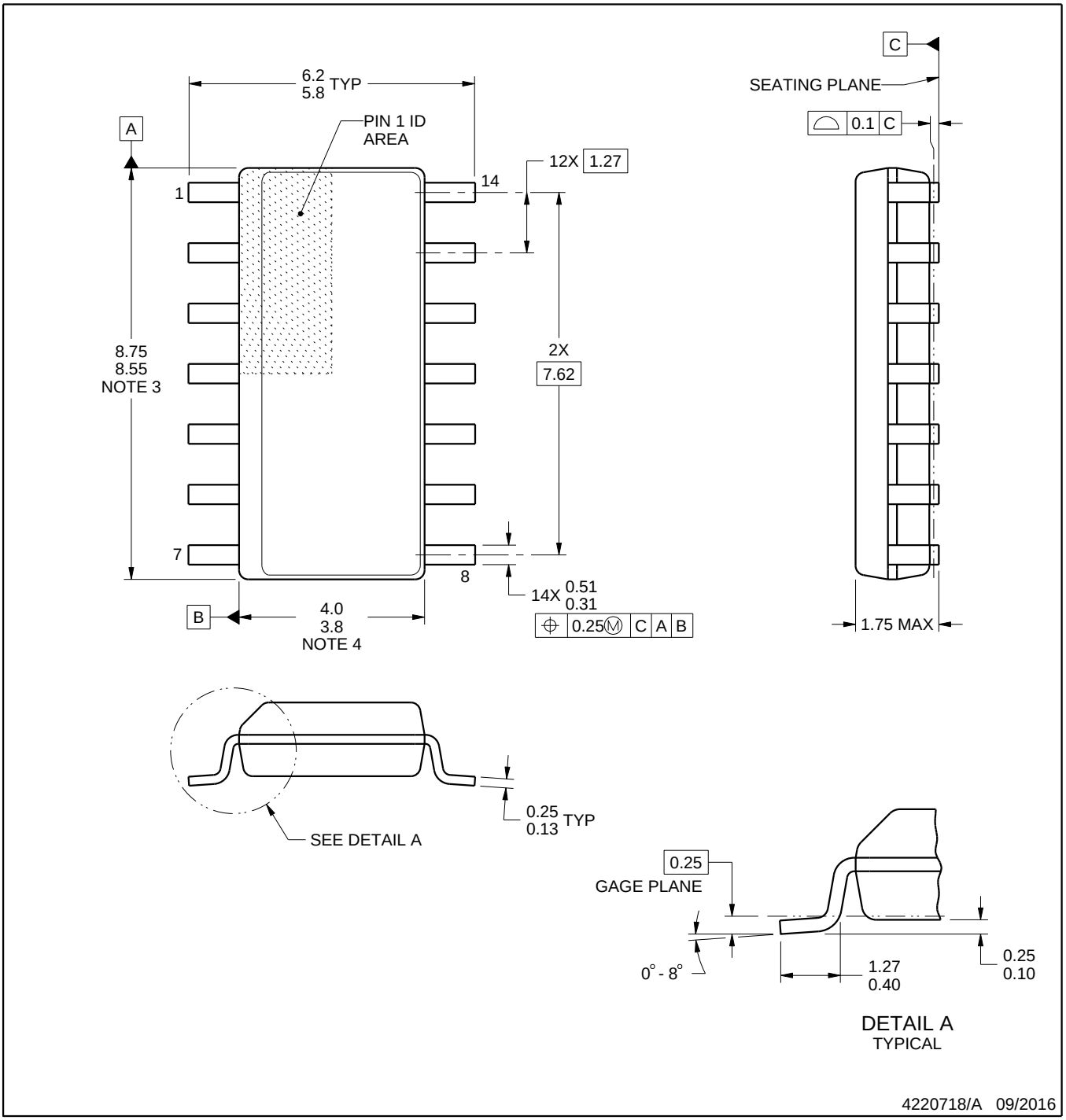


PACKAGE OUTLINE

D0014A

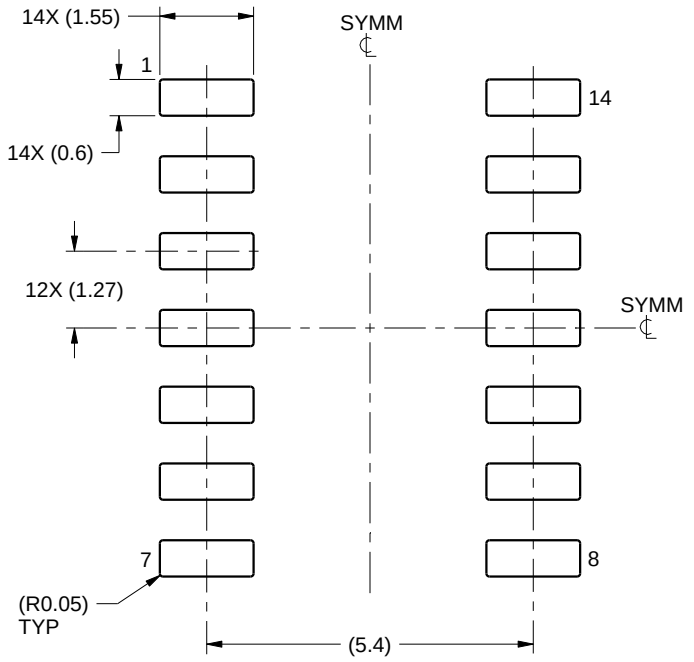
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

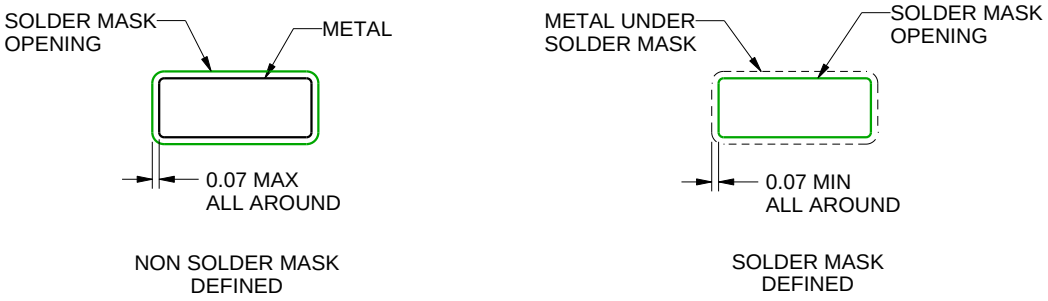


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

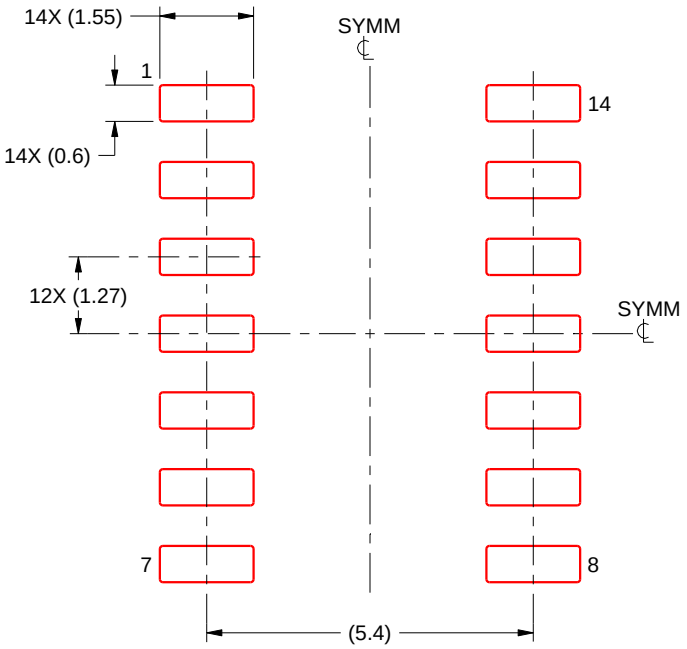
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

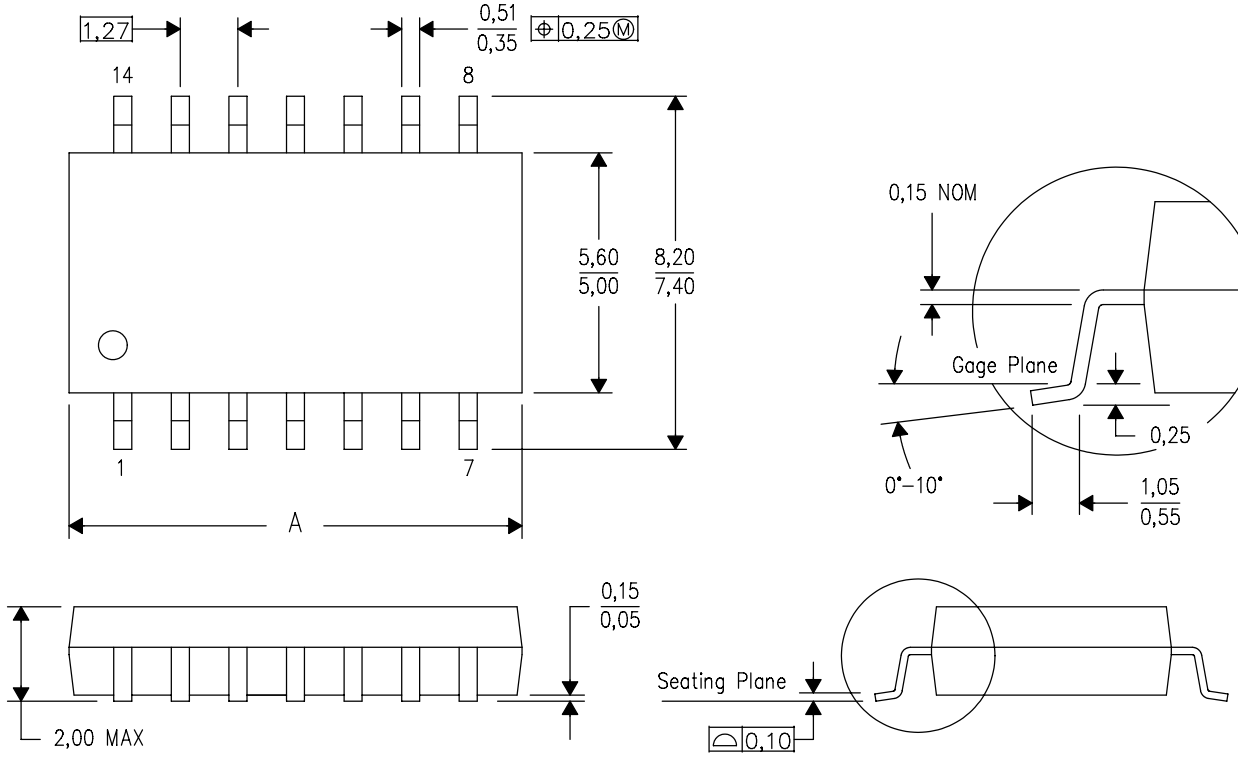
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

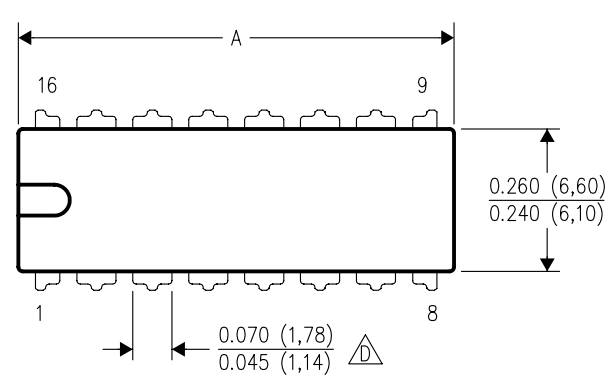
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

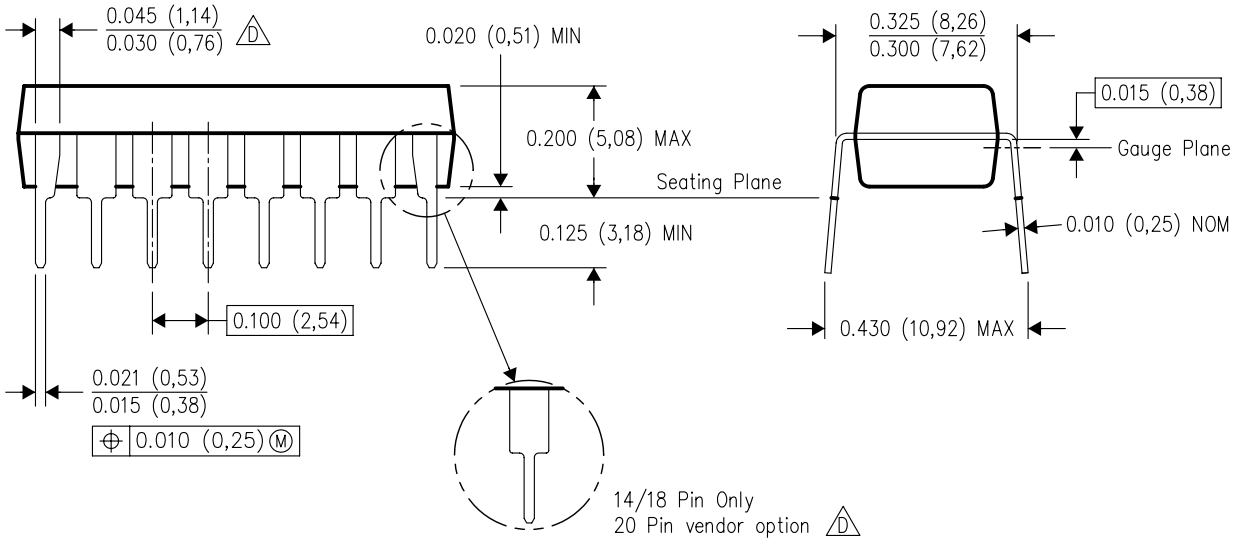
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265